

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
• (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
END920010002US1

In Re Application: Ray et al.

SEP 10 2002

Serial No.

09/779,812

Filing Date

2/8/01

Examiner

Nguyen, Ha T.

Group Art Unit

2812

**LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

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Address to:

Assistant Commissioner for Patents  
Washington, D.C. 20231

## 37 CFR 1.97(b)

1.  The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

## 37 CFR 1.97(c)

2.  The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

 the statement specified in 37 CFR 1.97(e);

OR

 the fee set forth in 37 CFR 1.17(p).09/12/2002 MAHMED1 00000117 090457 09779812  
01-FC:126 180.00 CH